

SEMICONDUCTOR CIRCUIT WITH MECHANICALLY ATTACHED LID

ABSTRACT OF THE DISCLOSURE

One aspect of the invention is a semiconductor circuit comprising a semiconductor die electrically  
5 connected to a package substrate through a plurality of electrical contacts. A lid above and substantially parallel to the top surface of the die forms a portion of the semiconductor circuit package. A plurality of lid supports each comprising a post and standoff member  
10 collectively create a separation between the lid and top surface of the die.